

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5	"361"/\$.ccls. and spacer with circuit adj board with (land pad terminal) and weld\$3 and plat\$3	USPAT; EPO; JPO	OR	ON	2004/12/07 12:31
L2	1	"174"/\$.ccls. and spacer with circuit adj board with (land pad terminal) and weld\$3 and plat\$3	USPAT; EPO; JPO	OR	ON	2004/12/07 12:31
L3	0	"29"/\$.ccls. and spacer with circuit adj board with (land pad terminal) and weld\$3 and plat\$3	USPAT; EPO; JPO	OR	ON	2004/12/07 12:32
L4	4	"257"/\$.ccls. and spacer with circuit adj board with (land pad terminal) and weld\$3 and plat\$3	USPAT; EPO; JPO	OR	ON	2004/12/07 12:33
L5	16	"257"/\$.ccls. and (core spacer) with circuit adj board with (land pad terminal) and (inject\$3 fill\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:36
L6	5	"29"/\$.ccls. and (core spacer) with circuit adj board with (land pad terminal) and (inject\$3 fill\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:37
L7	13	"174"/\$.ccls. and (core spacer) with circuit adj board with (land pad terminal) and (inject\$3 fill\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:38
L8	15	"361"/\$.ccls. and (core spacer) with circuit adj board with (land pad terminal) and (inject\$3 fill\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:38
L9	58	"361"/\$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (encapsulat\$3 inject\$3 fill\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:42
L10	61	"174"/\$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (encapsulat\$3 inject\$3 fill\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:44
L11	50	"29"/\$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (encapsulat\$3 inject\$3 fill\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:45
L12	87	"361"/\$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (deposit\$3 cur\$3 encapsulat\$3 inject\$3 fill\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:51

L13	38	("4813129").URPN.	USPAT	OR	ON	2004/12/07 12:49
L14	94	"361"/\$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (core spacer) with (weld\$3 plat\$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 12:55
L15	94	"29"/\$.ccls. and (core spacer) with (substrate board) with (land pad terminal) and (core spacer) with (weld\$3 plat\$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:31
L16	0	"29"/\$.ccls. and spacer with (substrate board) with (land pad terminal) and control\$3 near3 collaps\$3 near3 chip near3 connect\$3 with (weld\$3 plat\$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:32
L17	0	spacer with (substrate board) with (land pad terminal) and control\$3 near3 collaps\$3 near3 chip near3 connect\$3 with (weld\$3 plat\$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:33
L18	0	spacer with (land pad terminal) and control\$3 near3 collaps\$3 near3 chip near3 connect\$3 with (weld\$3 plat\$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:33
L19	2	spacer with (land pad terminal) and control\$3 near3 collaps\$3 near3 chip near3 connect\$3 same (weld\$3 plat\$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:33
L20	6	spacer with (land pad terminal) same (weld\$3 plat\$3) and control\$3 near3 collaps\$3 near3 chip near3 connect\$3	USPAT; EPO; JPO	OR	ON	2004/12/07 15:34
L21	92	spacer with (land pad terminal) same (weld\$3 plat\$3) and ("4c" "4-c")	USPAT; EPO; JPO	OR	ON	2004/12/07 15:37
L22	9	"361"/\$.ccls. and spacer near3 plat\$3 with (land pad terminal) and (deposit\$3 insert\$3 inject\$3 fill\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:40
L23	27	"361"/\$.ccls. and spacer with (land pad terminal) same (board substrate) and spacer near3 plat\$3	USPAT; EPO; JPO	OR	ON	2004/12/07 15:42
L24	0	"361"/\$.ccls. and spacer with (land pad terminal) same (board substrate) and spacer near3 weld\$3	USPAT; EPO; JPO	OR	ON	2004/12/07 15:42
L25	234	spacer with (land pad terminal) same (board substrate) and spacer near4 (plat\$3 weld\$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 17:06
L26	113	spacer with (land pad terminal) same (board substrate) and spacer near4 (plat\$3 weld\$3) with (land pad terminal)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:56

L28	731	spacer with (land pad terminal) same (board substrate) and (deposit\$3 insert\$3 inject\$3 fill\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/07 15:56
L29	17	spacer with (land pad terminal) same (board substrate) and (deposit\$3 insert\$3 inject\$3 fill\$3) with (epoxy insulat\$3 dielectric) and partial\$2 near3 cur\$3	USPAT; EPO; JPO	OR	ON	2004/12/07 15:58
L30	45	spacer with (land pad terminal) same (board substrate) and (deposit\$3 insert\$3 inject\$3 fill\$3) with (epoxy insulat\$3 dielectric) same cur\$3	USPAT; EPO; JPO	OR	ON	2004/12/07 15:59
L31	31	("5037312").URPN.	USPAT	OR	ON	2004/12/07 17:18
L32	15	29/\$.ccls. and spacer with (land pad terminal) same (board substrate) and spacer near4 (plat\$3 weld\$3)	USPAT; EPO; JPO	OR	ON	2004/12/07 17:08
L33	43	29/\$.ccls. and spacer with (land pad terminal) same (board substrate) and solder	USPAT; EPO; JPO	OR	ON	2004/12/07 17:08
L34	116	361/758.CCLS.	USPAT	OR	ON	2004/12/07 17:18
S1	4	sundahl.in. and interconnect\$.ti.	US-PGPUB; USPAT; EPO; JPO	OR	ON	2004/11/30 10:26
S2	23	("4693770" "4818728" "5233504" "5311059" "5583350" "5659203" "5703394" "5722161" "5726502" "5764485" "5767580" "5795818" "5801446" "5838069" "5858806" "5861678" "5889568" "5907187" "5912505" "5987358" "6018197" "6040631" "6324754").PN.	USPAT; EPO; JPO	OR	ON	2004/12/03 16:41
S3	2	LED same spacer same glass near3 (substrate board) and (ceramic printed) near3 board	USPAT; EPO; JPO	OR	ON	2004/12/03 16:53
S4	58	display same spacer same glass near3 (substrate board) and (ceramic printed) near3 board	USPAT; EPO; JPO	OR	ON	2004/12/03 17:01
S5	28	display and spacer same electrode and glass near3 (substrate board) and (ceramic printed) near3 board and (opto\$1electric\$3 processor)	USPAT; EPO; JPO	OR	ON	2004/12/03 17:56
S6	42	(lcd led) and align\$3 same (spacer core spherical) with member and (glass ceramic) with (substrate board)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:35

S7	59	align\$3 same (spacer core spherical) with member and (glass ceramic) with (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:40
S8	470	align\$3 same spacer and (glass ceramic) near3 (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:41
S9	21	align\$3 same spacer with (terminal pad land) and (glass ceramic) near3 (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:47
S10	4	align\$3 same spacer with (terminal pad land) and glass near3 (substrate board) same ceramic near3 (substrate board)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:45
S11	11	align\$3 same spacer with (terminal pad land) and glass near3 (substrate board) and ceramic near3 (substrate board)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:45
S12	12	("5136365" "5187020" "5375042" "5412539" "5509200" "5518674" "5805426" "5893765" "5905638" "5910641" "6090633" "6326561").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:46
S13	9	align\$3 same core with (terminal pad land) and (glass ceramic) near3 (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:55
S14	7	("5108027" "5431328" "5838069" "5971253" "6087597" "6278184" "6337445").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:48
S15	3	("5431328" "5868304" "5956235").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:50
S16	21	("3089062" "3331912" "3392442" "4020987" "4640438" "4746583" "5153709" "5268815" "5294830" "5324892" "5329160" "5372295" "5414300" "5471027" "5517753" "5523260" "5551627" "5881945").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:51

S17	31	("4001870" "4365264" "4538105" "4618878" "4695870" "4716049" "4792532" "4813129" "4902606" "4994735" "5020219" "5070297" "5072520" "5103557" "5120665" "5135890" "5148265" "5148266" "5153507" "5180311" "5321583" "5393697" "5430329" "5431328" "5440241" "5455390" "5578527" "5604380" "5666270" "5679977" "5749997").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:52
S18	12	("3401126" "3809625" "4402450" "4705205" "4749120" "4903889" "4916523" "4963002" "5134460" "5329423").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 16:54
S19	6	align\$3 same spherical with (terminal pad land) and (glass ceramic) near3 (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 16:56
S20	44	align\$3 same solder near2 ball with (terminal pad land) and (glass ceramic) near3 (substrate board) with (two second multiple)	USPAT; EPO; JPO	OR	ON	2004/12/06 18:46
S21	5	align\$3 same solder near2 ball with (terminal pad land) and (glass ceramic) near3 (substrate board) and injecting with (epoxy insulat\$3 dielectric) same curing	USPAT; EPO; JPO	OR	ON	2004/12/06 18:48
S22	5	align\$3 same solder near2 ball with (terminal pad land) and (glass ceramic) near3 (substrate board) and injecting with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/06 18:48
S23	0	align\$3 same spacer with (terminal pad land) and (glass ceramic) near3 (substrate board) and injecting with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/06 18:48
S24	8	align\$3 same spacer with (terminal pad land) and (glass ceramic) near3 (substrate board) and (fill\$3 inject\$3) with (epoxy insulat\$3 dielectric)	USPAT; EPO; JPO	OR	ON	2004/12/06 18:49
S25	15	("4617730" "4954878" "5010038" "5086558" "5218234" "5426072" "5447264" "5468681" "5504035" "5817541" "5821624" "5866949" "5915169" "6020220" "6242815").PN.	US-PGPUB; USPAT; USOCR	OR	ON	2004/12/06 18:49